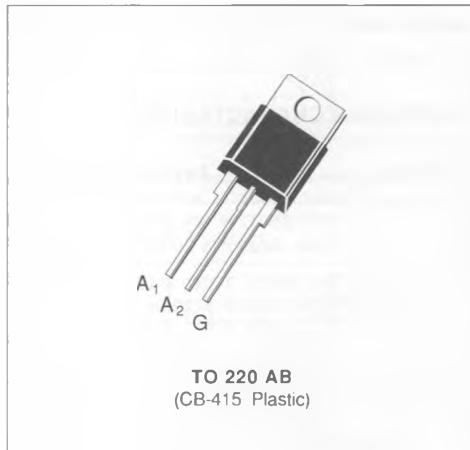


SNUBBERLESS TRIACS

- $I_{TRMS} = 16 \text{ A}$ at $T_c = 90^\circ\text{C}$.
- V_{DRM} : 200 V to 800 V.
- $I_{GT} = 35 \text{ mA}$ (Q1-II-III).
- GLASS PASSIVATED CHIP.
- HIGH SURGE CURRENT : $I_{TSM} = 150 \text{ A}$.
- HIGH COMMUTATION CAPABILITY :
 $(di/dt)_c > 8.5 \text{ A / ms}$ without snubber.


DESCRIPTION

New range suited for applications such as phase control and static switching on inductive or resistive load.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value		Unit
I_{TRMS}	RMS on-state current (360 ° conduction angle)	$T_c = 90^\circ\text{C}$	16	A
I_{TSM}	Non repetitive surge peak on-state current (T_j initial = 25 °C)	$t = 8.3 \text{ ms}$	157	A
		$t = 10 \text{ ms}$	150	
I^2t	I^2t value	$t = 10 \text{ ms}$	112	A^2s
di/dt	Critical rate of rise of on-state current (1)	Repetitive $F = 50 \text{ Hz}$	20	$\text{A}/\mu\text{s}$
		Non Repetitive	100	
T_{stg} T_c	Storage and operating junction temperature range	- 40, + 150 - 40, + 125		°C

Symbol	Parameter	BTB 16-					Unit
		200 CW	400 CW	600 CW	700 CW	800 CW	
V_{DRM}	Repetitive peak off-state voltage (2)	± 200	± 400	± 600	± 700	± 800	V

(1) Gate supply : $I_G = 350 \text{ mA}$ - $dI_G/dt = 1 \text{ A / } \mu\text{s}$.

(2) $T_j = 125^\circ\text{C}$.

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th} (j-a)	Junction to ambient	60	°C/W
R _{th} (j-c) DC	Junction to case for DC	2.4	°C/W
R _{th} (j-c) AC	Junction to case for 360 ° conduction angle (F = 50 Hz)	1.8	°C/W

GATE CHARACTERISTICS (maximum values)

P_{GM} = 40 W (t = 10 µs) P_{G(AV)} = 1 W I_{GM} = 4 A (t = 10 µs) V_{GM} = 16 V (t = 10 µs).

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Quadrants	Min.	Typ.	Max.	Unit
I _{GT}	T _j = 25 °C	V _D = 12 V	R _L = 33 Ω	I-II-III	1		35	mA
	Pulse duration > 20 µs							
V _{GT}	T _j = 25 °C	V _D = 12 V	R _L = 33 Ω	I-II-III			1.5	V
	Pulse duration > 20 µs							
V _{GD}	T _j = 125 °C	V _D = V _{DRM}	R _L = 3.3 kΩ	I-II-III	0.2			V
	Pulse duration > 20 µs							
I _H *	T _j = 25 °C Gate open	I _T = 100 mA R _L = 140 Ω					35	mA
I _L	T _j = 25 °C	V _D = 12 V	I _G = 350 mA	I-III			50	mA
	Pulse duration > 20 µs			II			80	
V _{TM} *	T _j = 25 °C	I _{TM} = 22.5 A	t _p = 10 ms				1.5	V
I _{DRM} *	T _j = 25 °C T _j = 125 °C	V _{DRM} rated	Gate open				0.01 2	mA
dV/dt *	T _j = 125 °C Linear slope up to 0.67 V _{DRM}	Gate open			250	500		V/µs
(dI/dt) _c +	T _j = 125 °C Without snubber	V _{DRM} rated			8.5	17		A/ms
t _{gt}	T _j = 25 °C I _T = 22.5 A	dI/dt = 1 A/µs V _D = V _{DRM}	I _G = 350 mA	I-II-III		2		µs

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

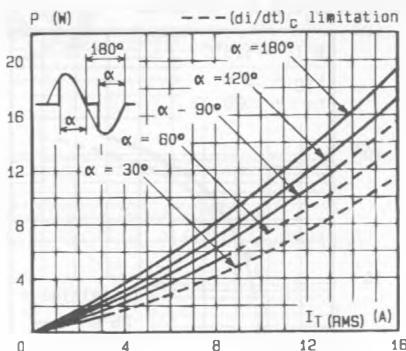


Fig.1 - Maximum mean power dissipation versus RMS on-state current ($F = 60$ Hz).

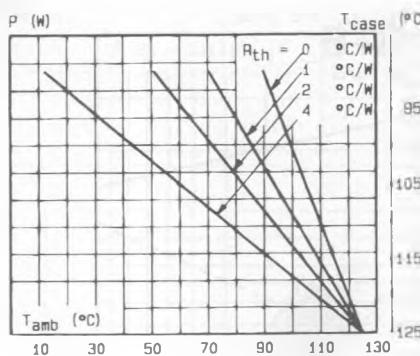


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

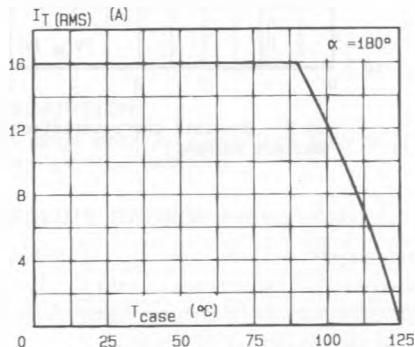


Fig.3 - RMS on-state current versus case temperature.

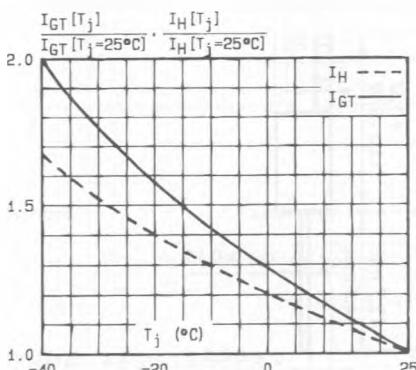


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

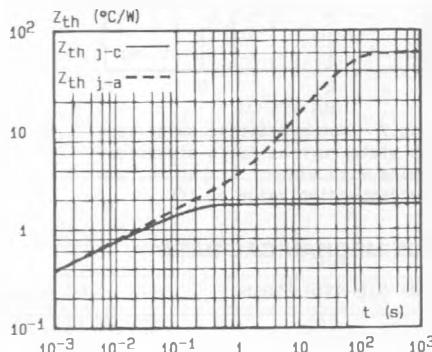


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

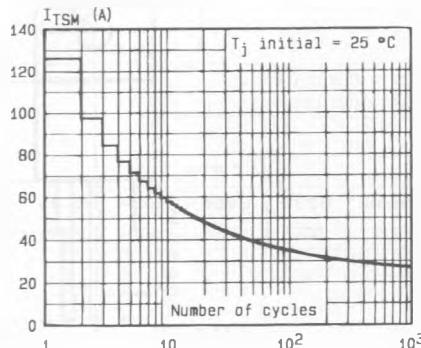


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

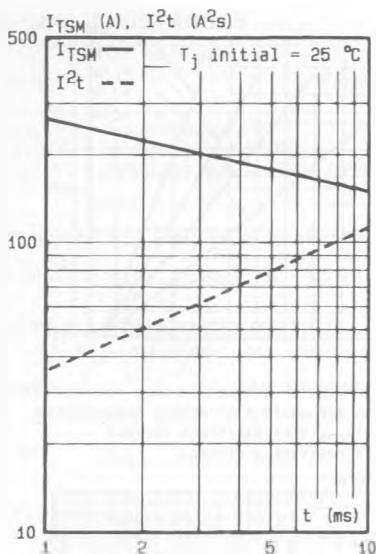


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .

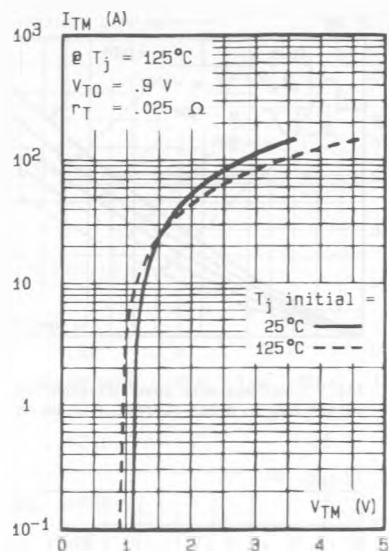
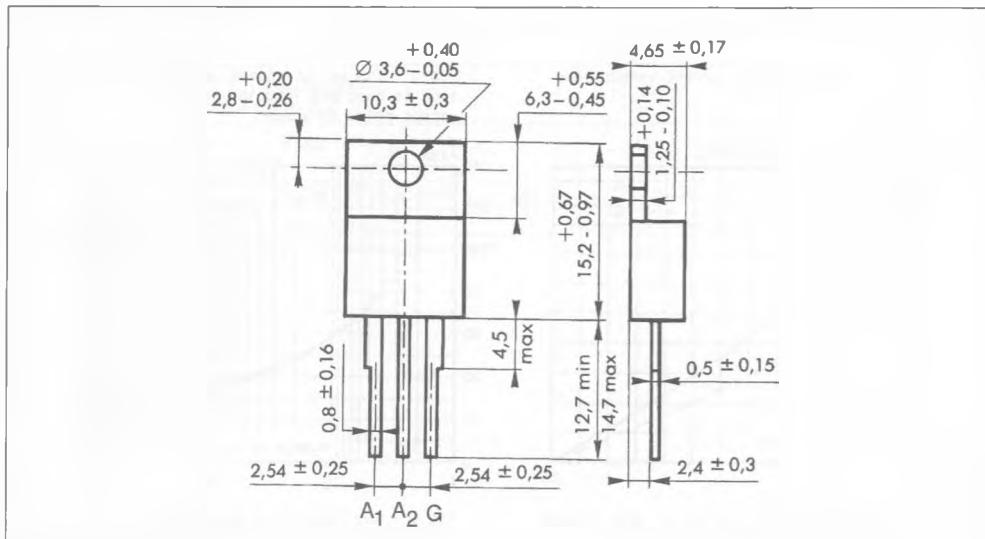


Fig.8 - On-state characteristics (maximum values).

PACKAGE MECHANICAL DATA

TO 220 AB (CB-415) Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g